



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of  
Shih, et al

Serial No.: 09/410,896

Filed: October 2, 1999

For: Apparatus and Method For Cooling A Semiconductor Substrate

Attorney Docket No.: 67,200-207

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# 5  
*[Signature]*

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to:  
Assistant Commissioner for Patents, Washington, D.C. 20231.

Date: August 22, 2001

*[Signature]*  
Kathy Dixon

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TRANSMITTAL OF FORMAL DRAWINGS

SEP - 4 2001

TECHNOLOGY CENTER R3700

Assistant Commissioner  
for Patents  
Washington, DC 20231

Sir:

Pursuant to an Office Action mailed May 23, 2001, enclosed herewith for filing is one set of formal drawings for the above-identified application.

Respectfully submitted,

TUNG & ASSOCIATES

*[Signature]*

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